

—

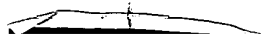


FIG. 2

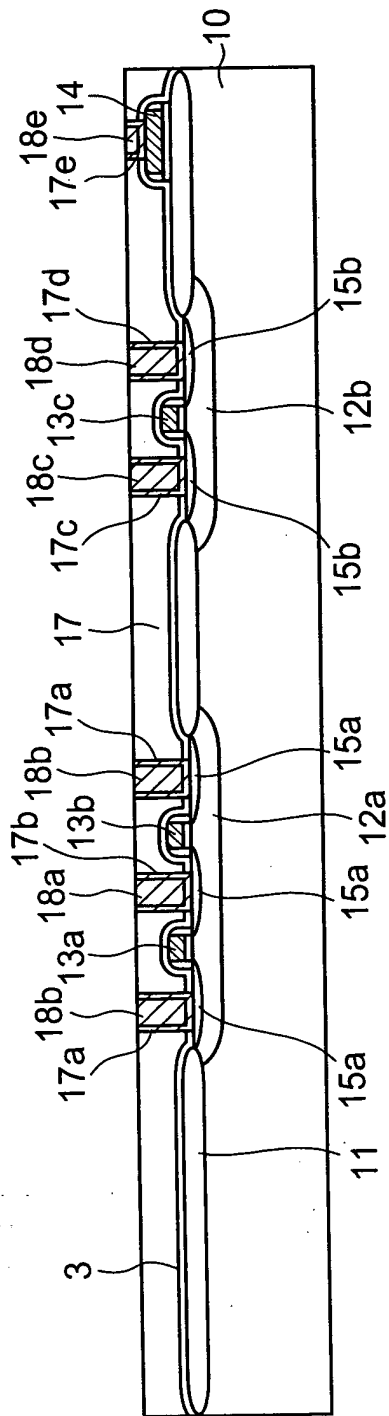


FIG. 3

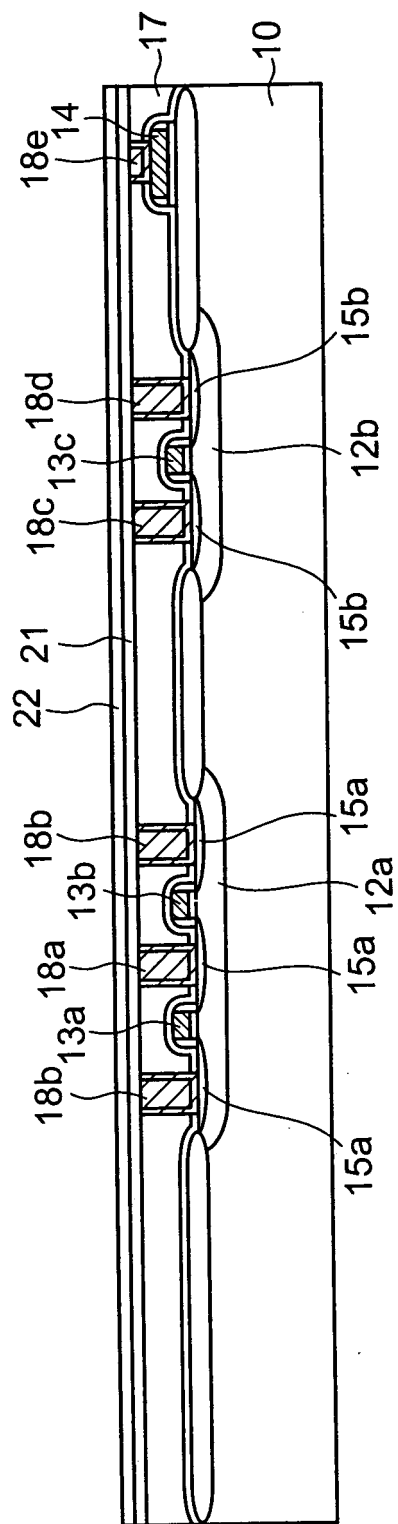
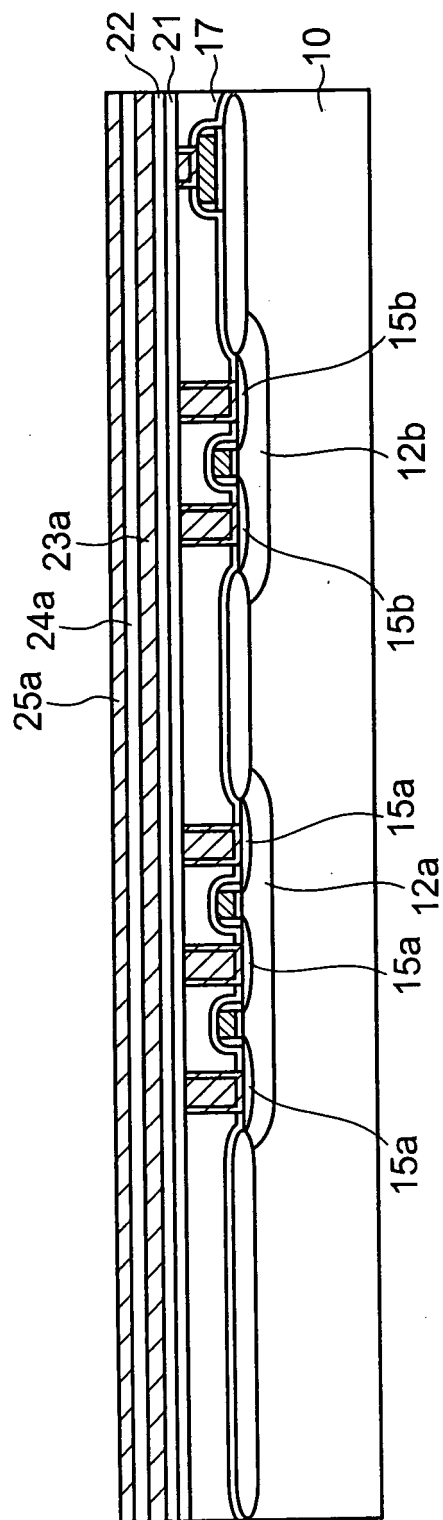


FIG. 4



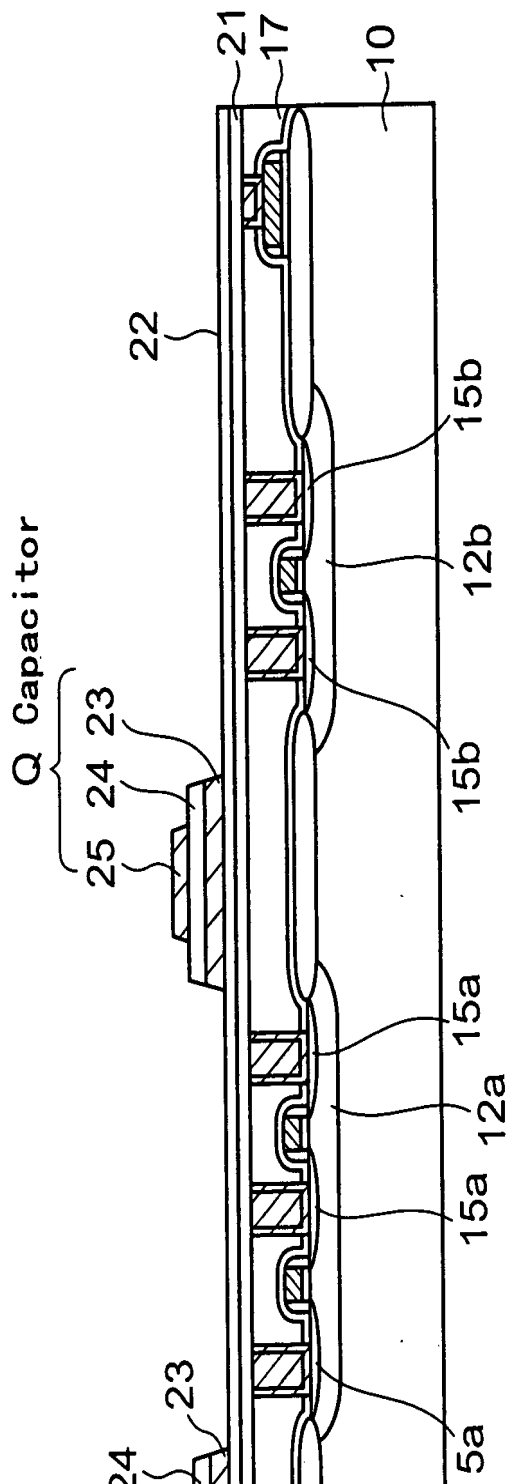


FIG. 5

FIG. 6

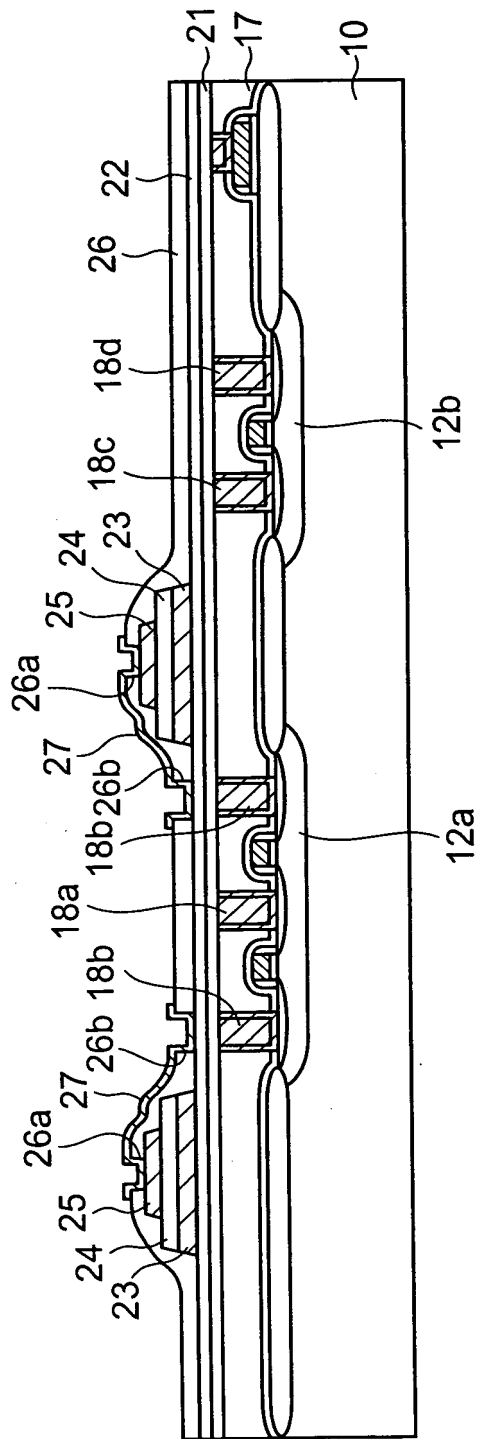


FIG. 7

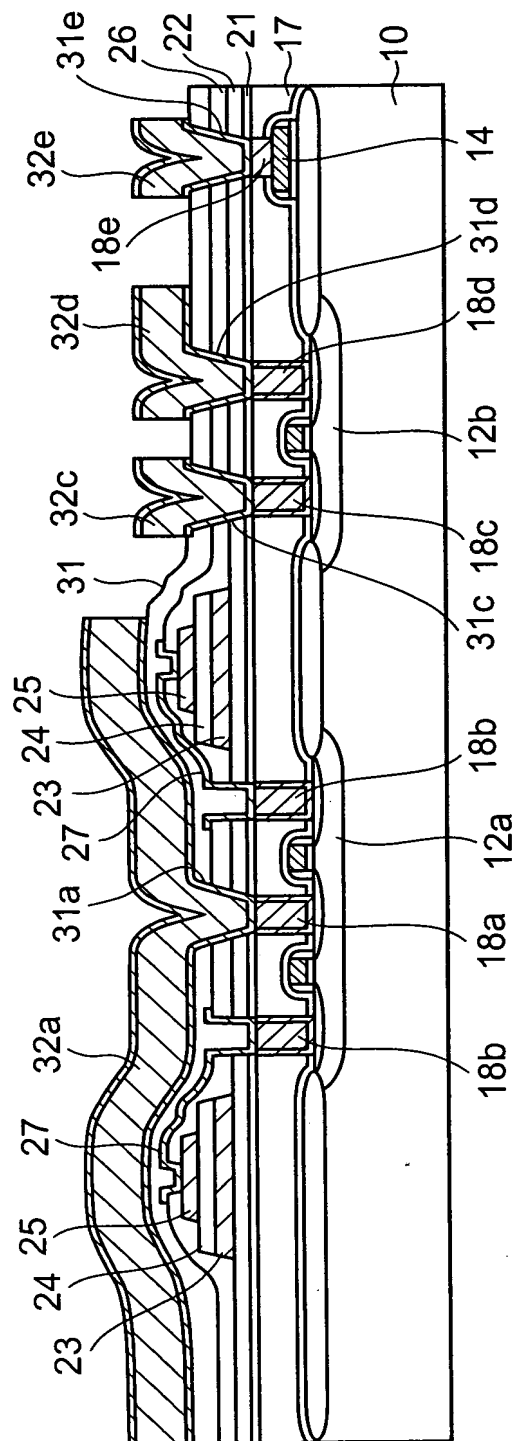


FIG. 8

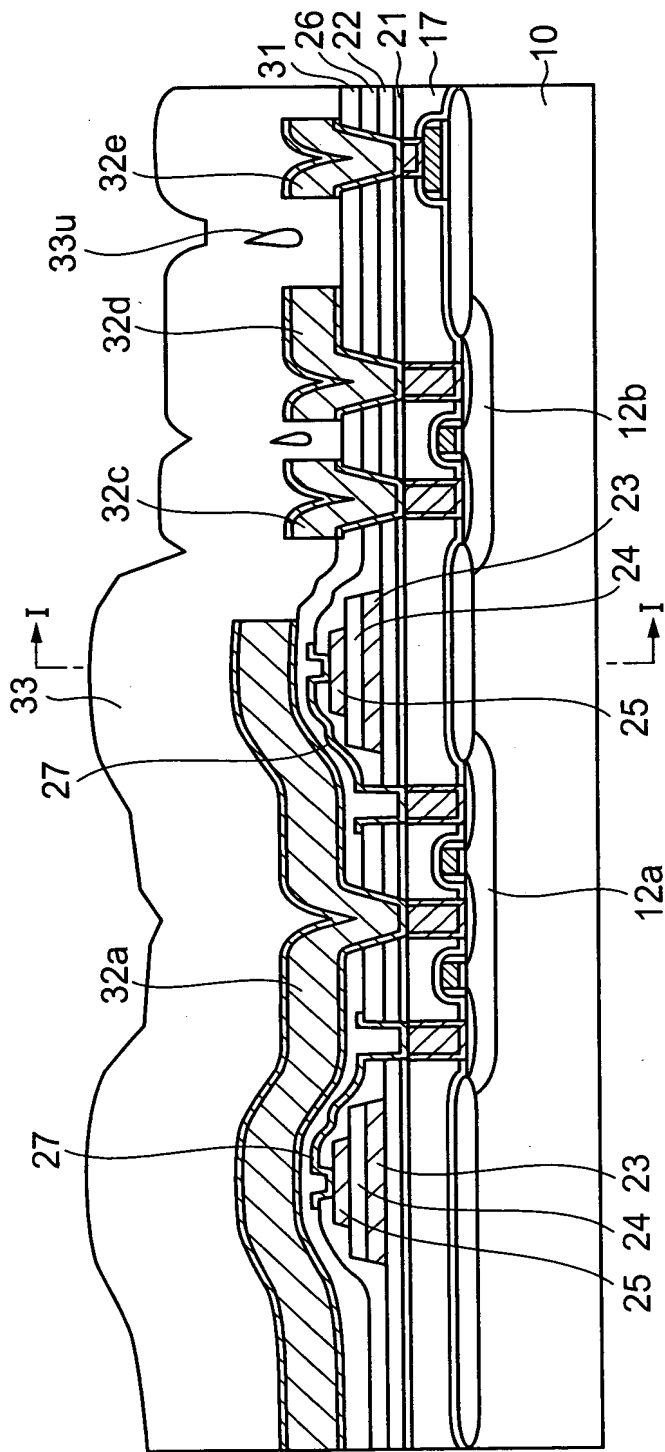




FIG. 9

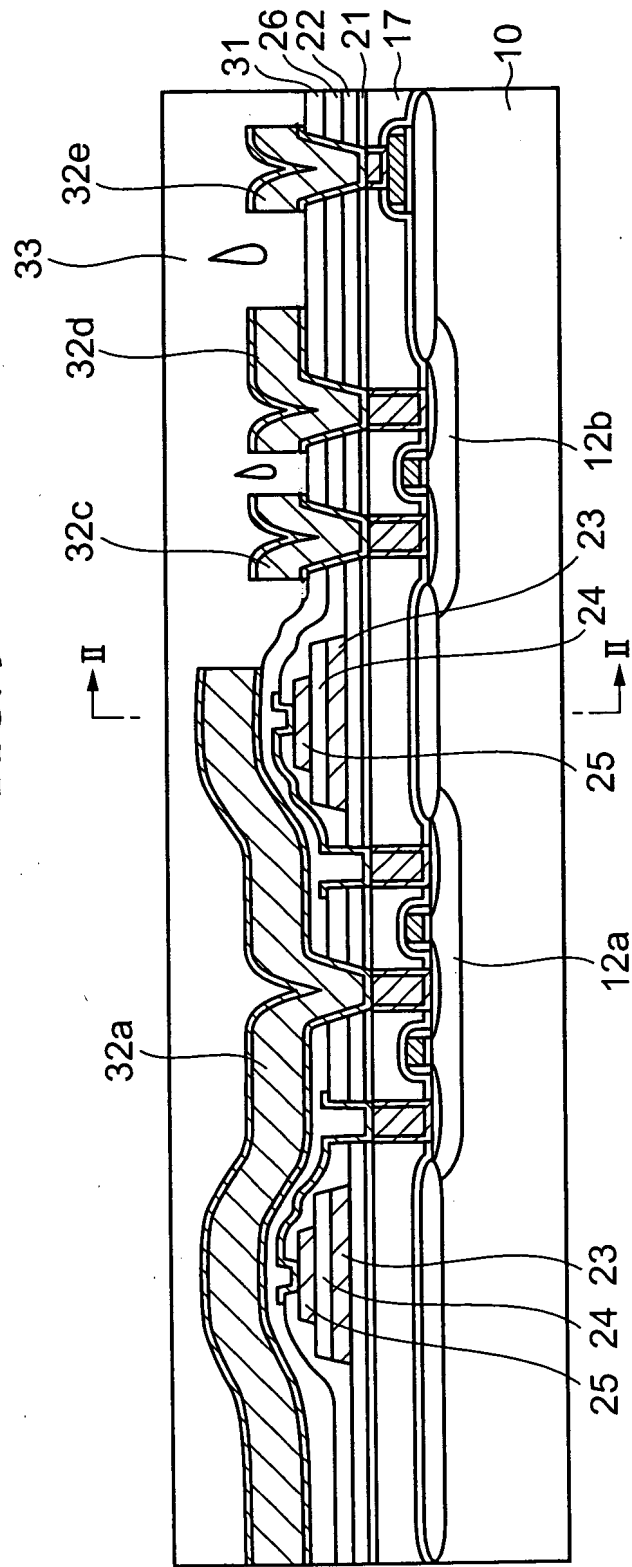


FIG. 10

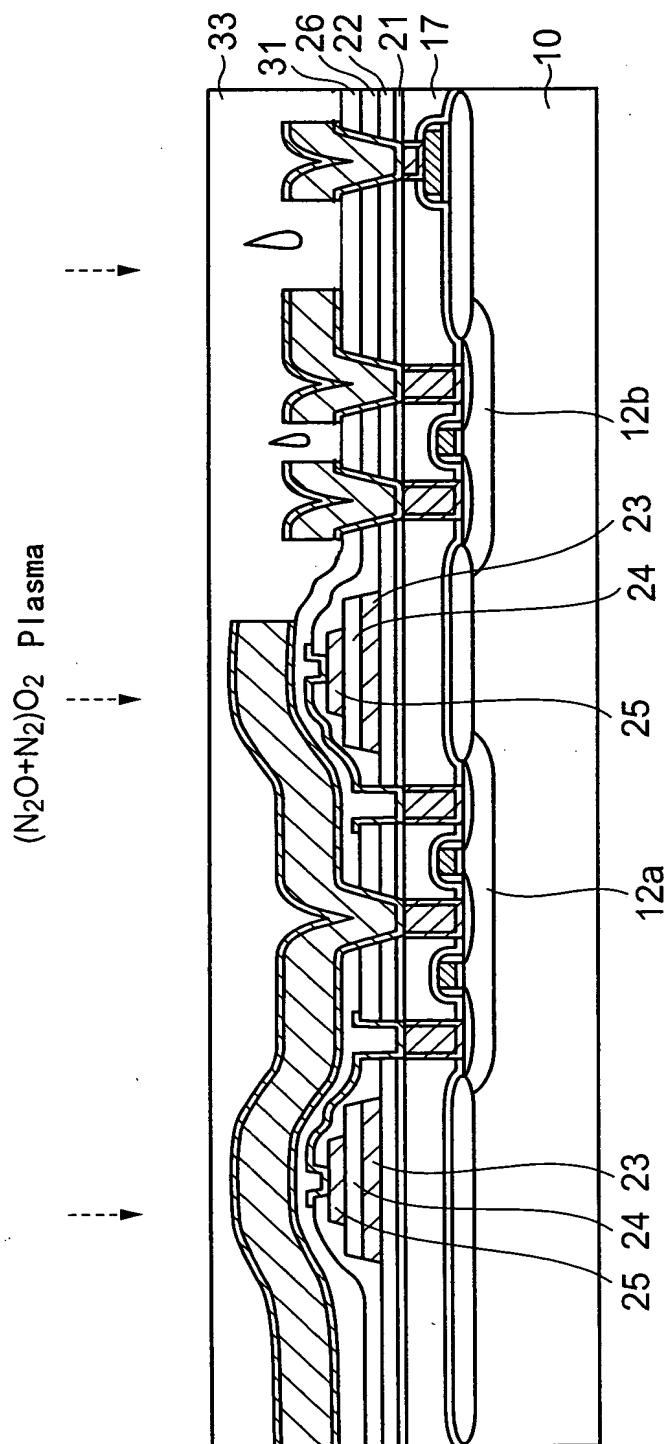


FIG. 11

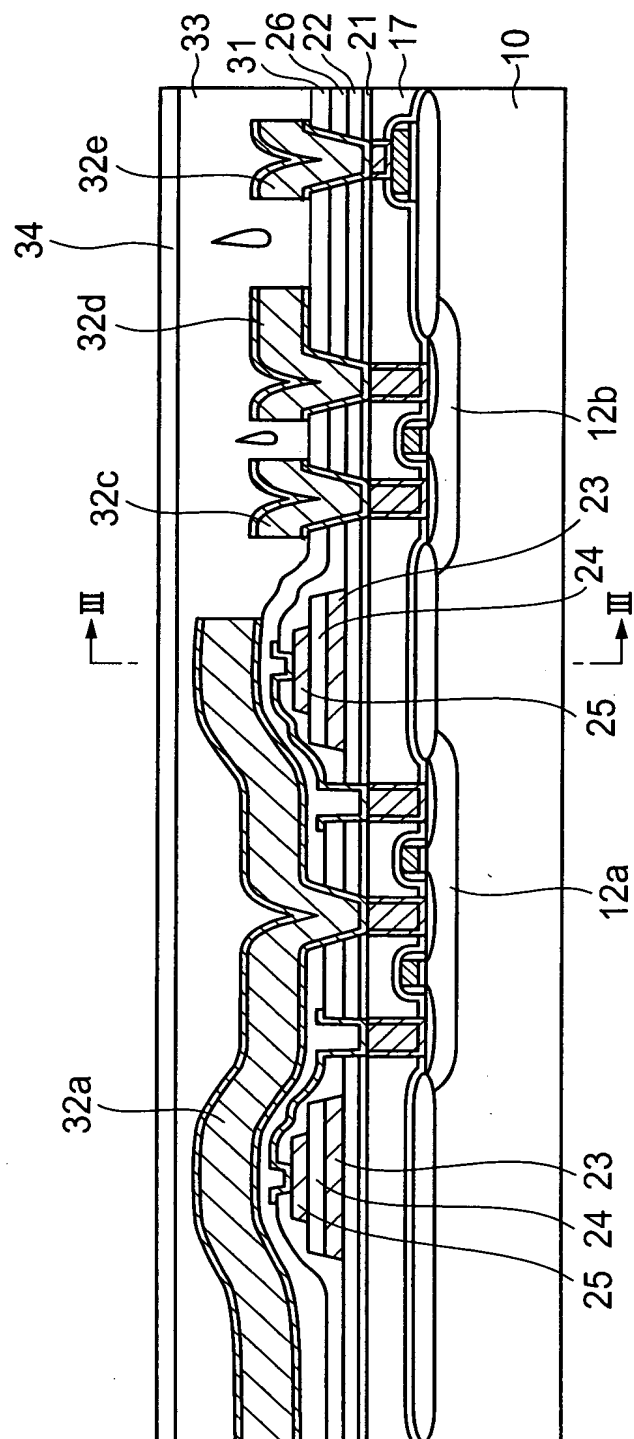


FIG. 12

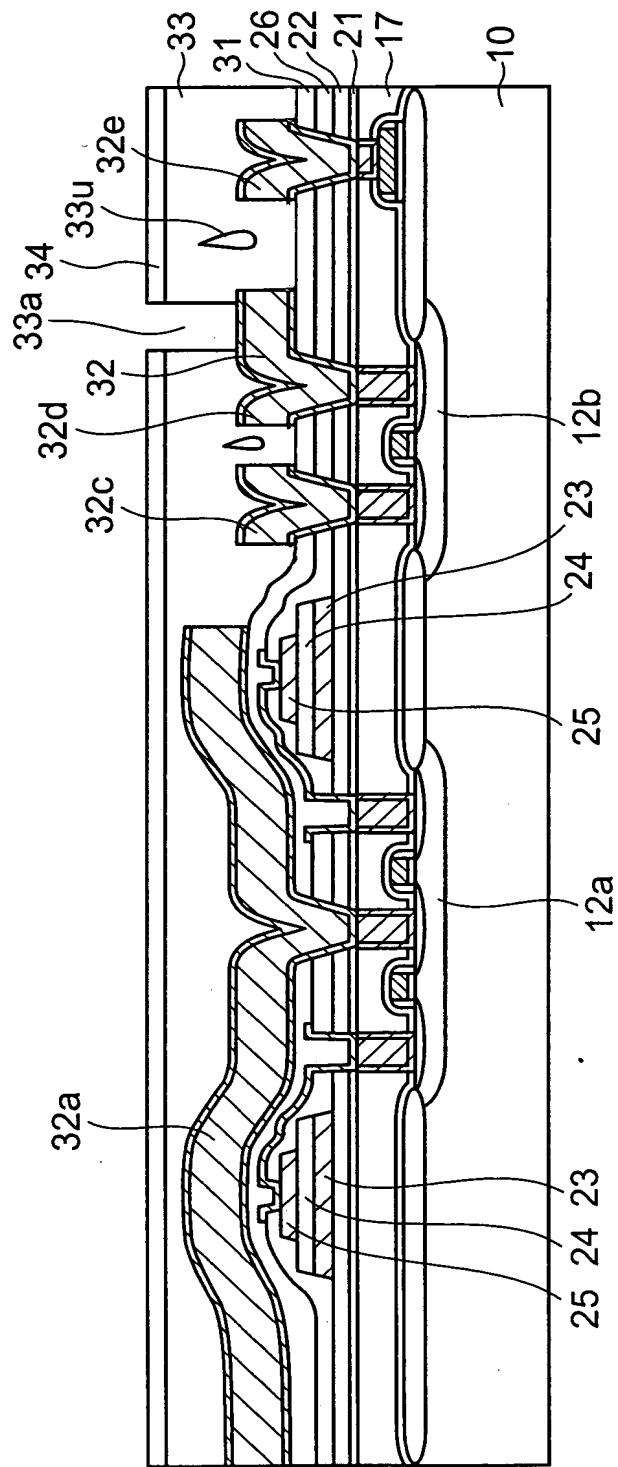


FIG. 13

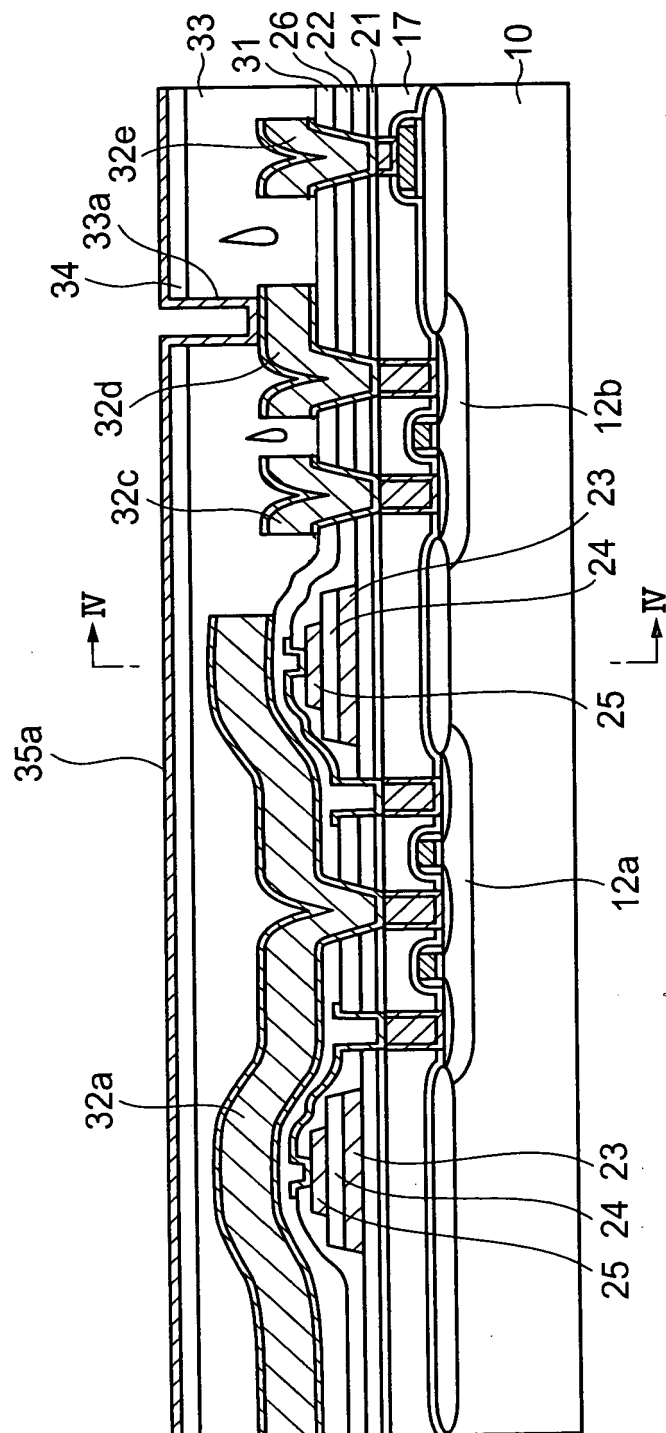
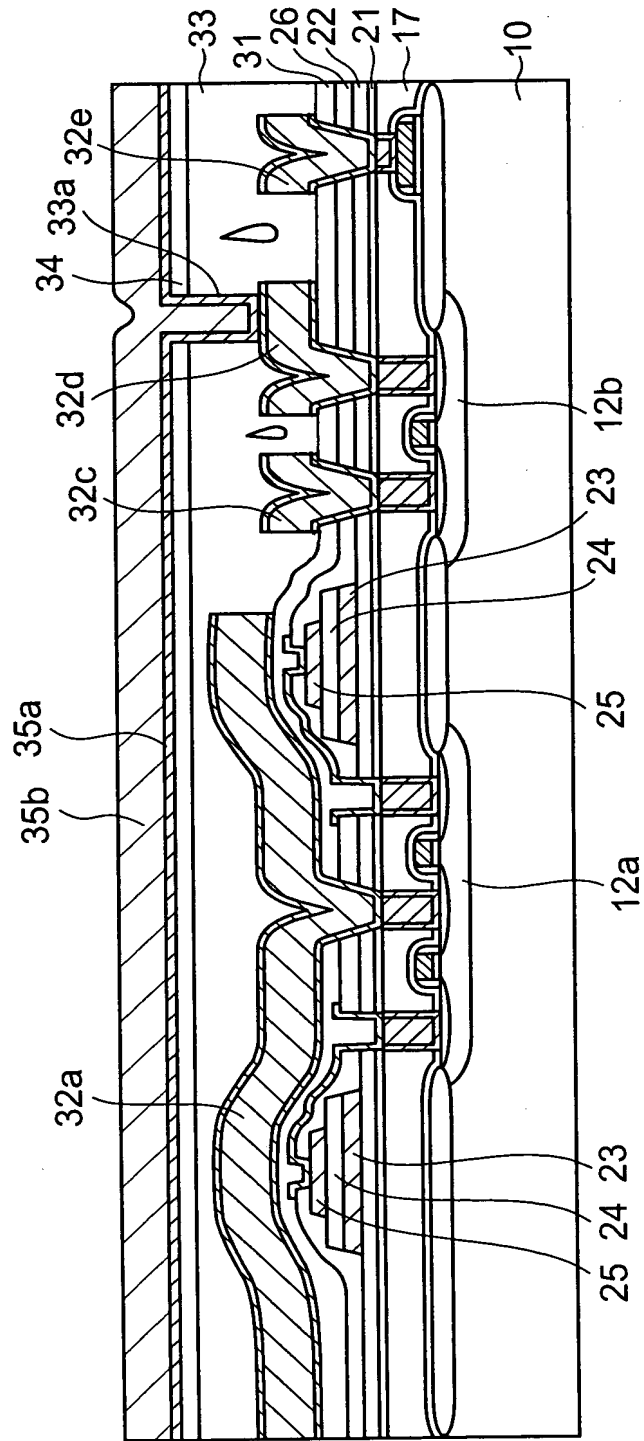


FIG. 14



This diagram shows a cross-sectional view of a multi-layered electronic device assembly. The assembly consists of several stacked layers, including a top layer (10), a middle layer (17), and a bottom layer (21). Various components are labeled with reference numerals: 31, 26, 22, 21, 17, 10, 33, 34, 35, 33a, 32c, 32a, 25, 24, 23, 12a, and 12b. The diagram illustrates the internal structure and the arrangement of these layers and components.

FIG. 16

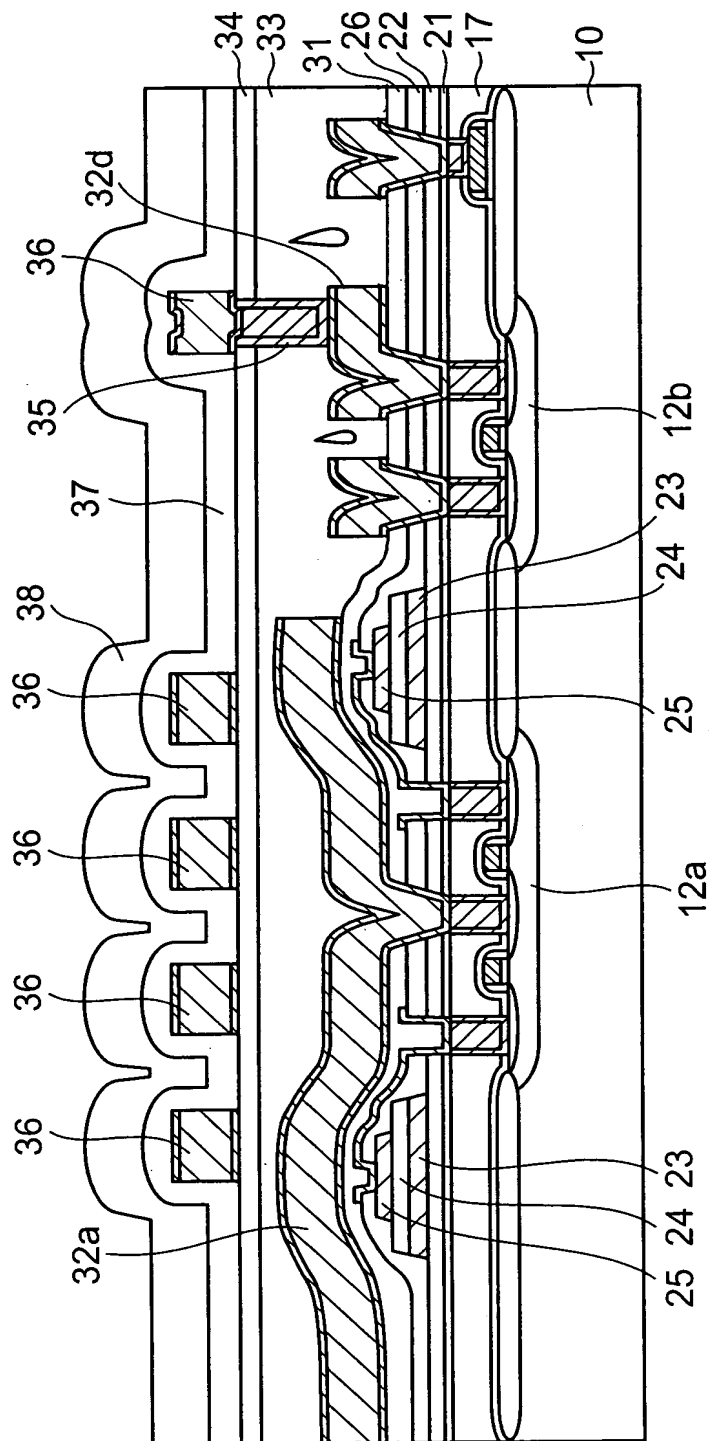




FIG. 17A

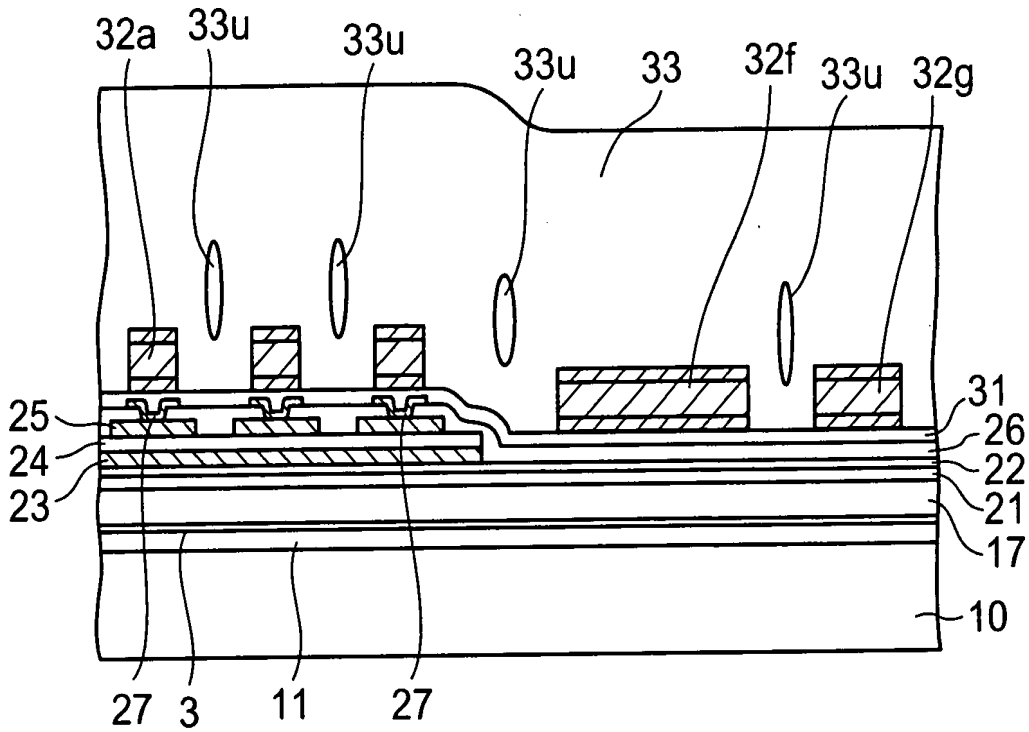
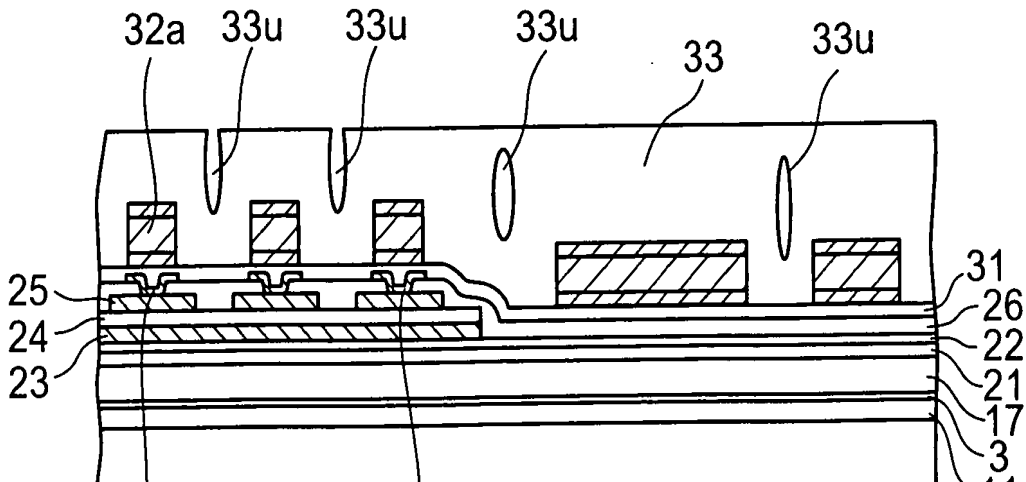


FIG. 17B



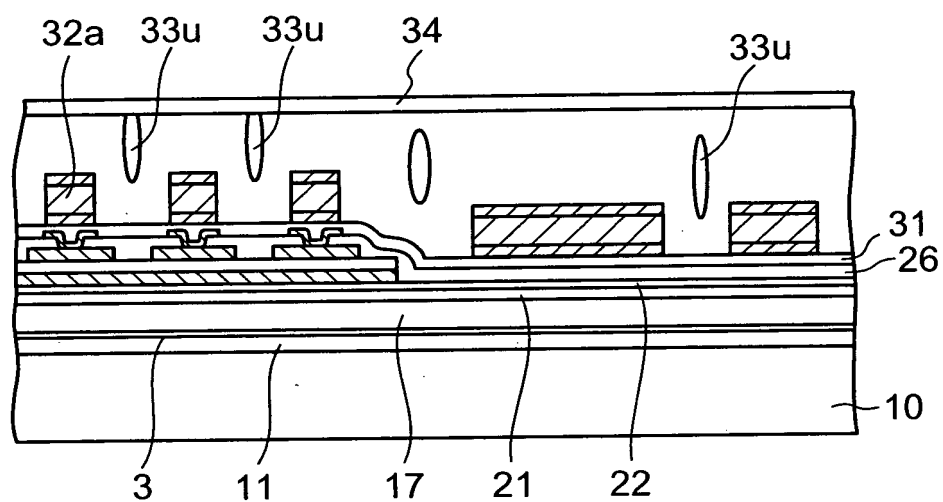
[illegible]

FIG. 17D

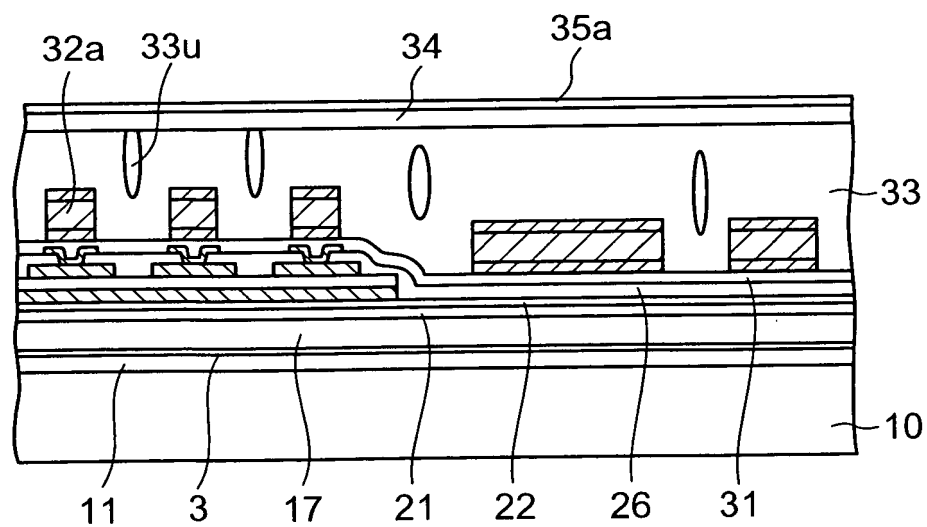


FIG. 18A

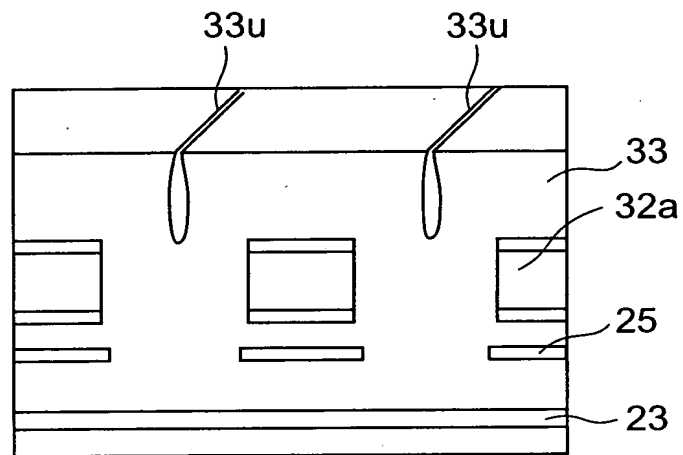
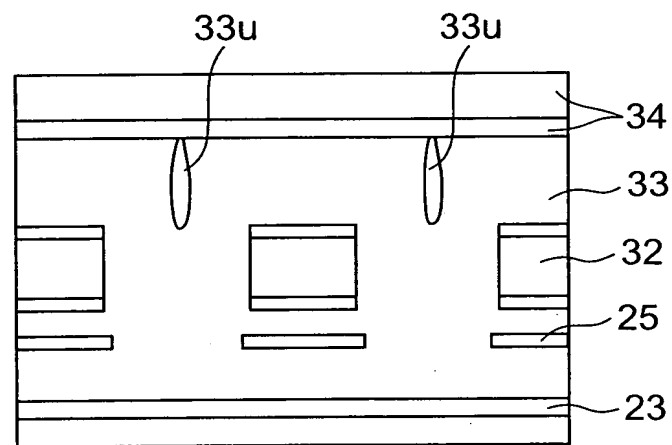


FIG. 18B



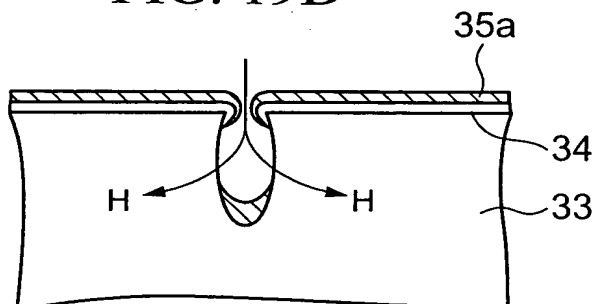
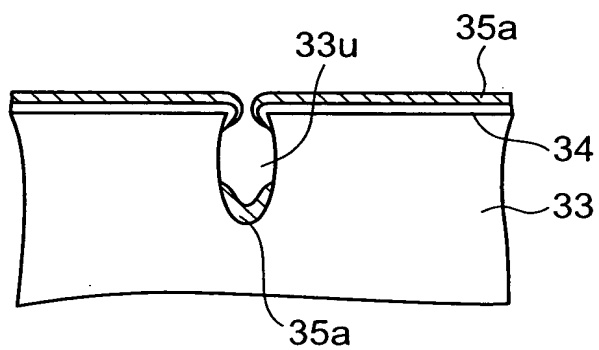
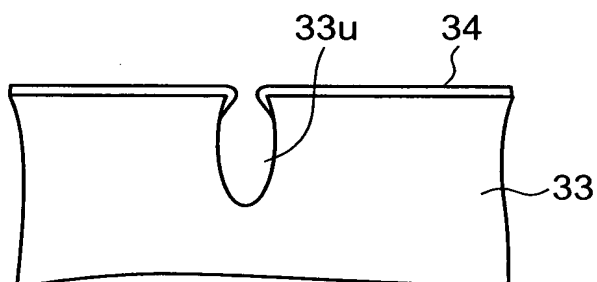
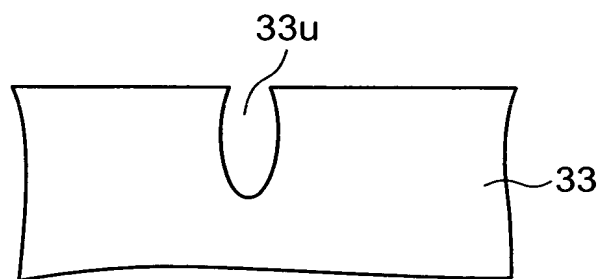


FIG. 20

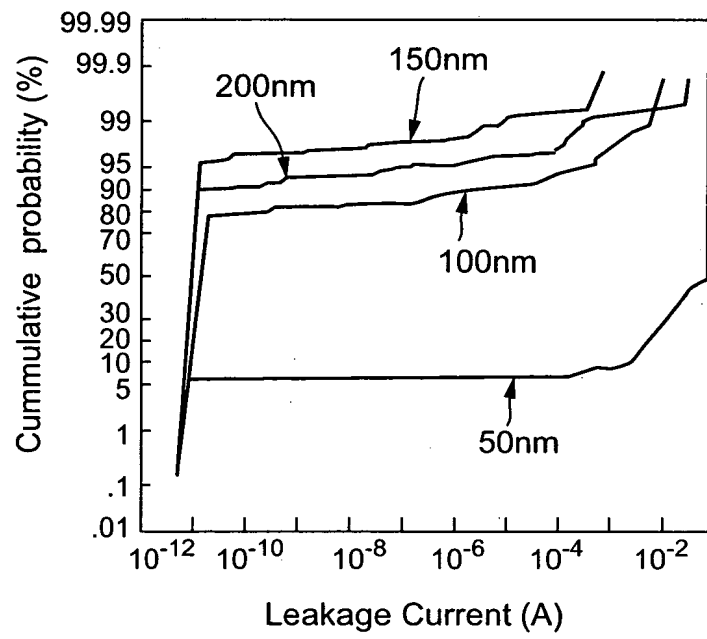


FIG. 21

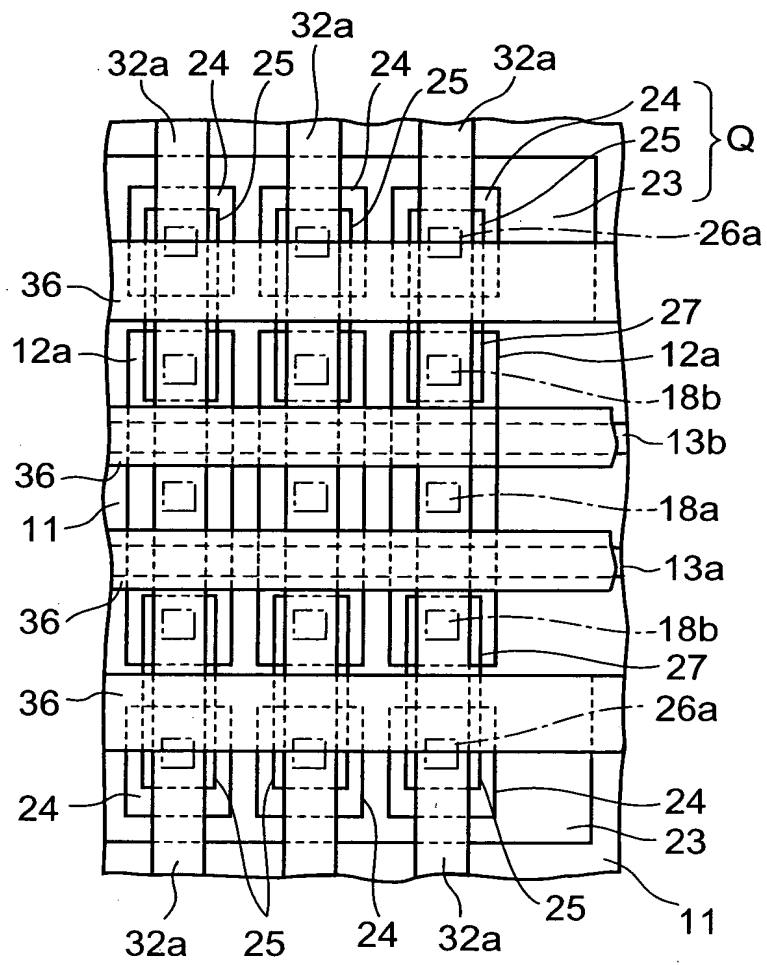


FIG. 22

